Fig.1

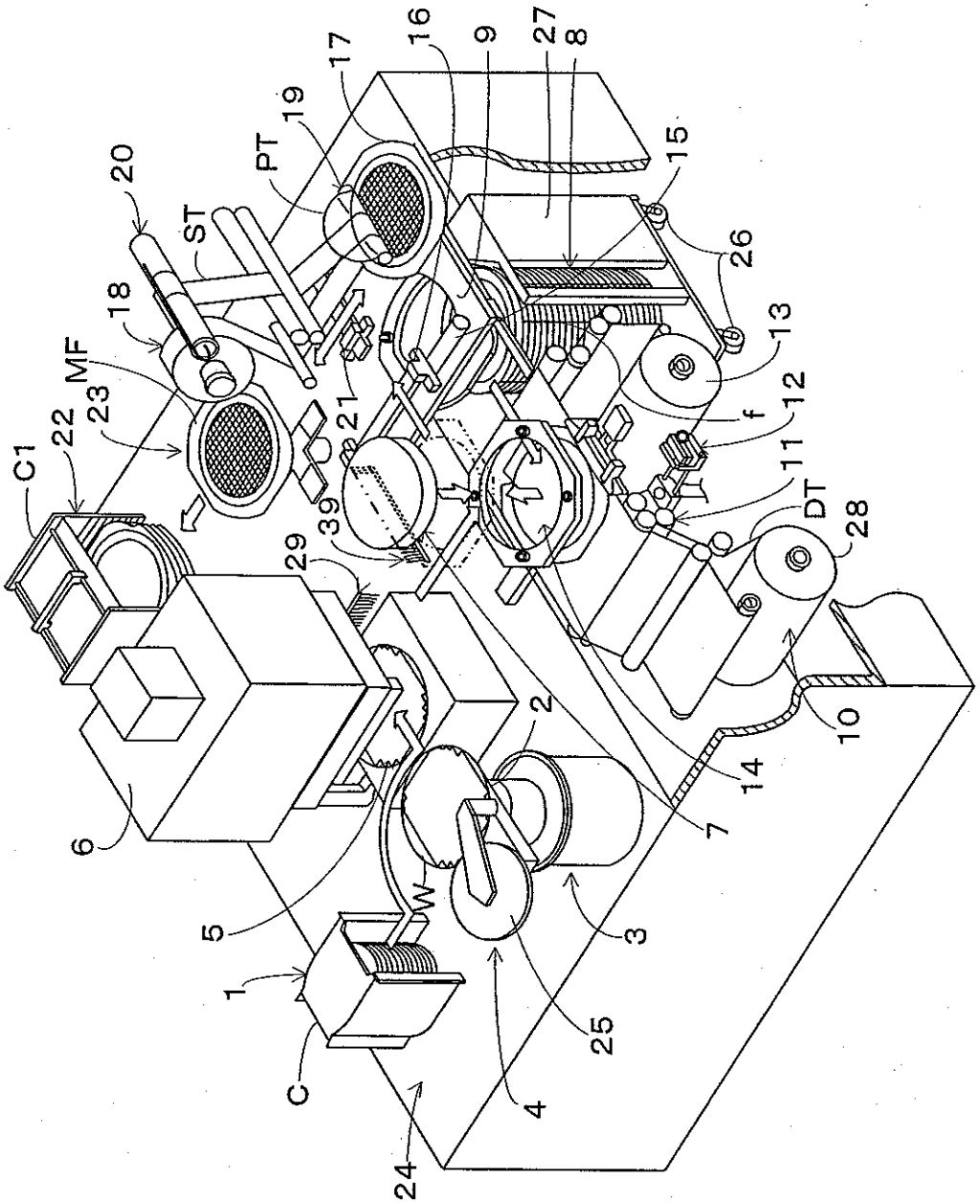

C1
22
MF
23
20
ST
18
PT
19
17
16
9
27
8
15
26
13
12
f
11
DT
28
10
14
7
2
29
39
21
6
5
1
C
W
3
25
4
24

Fig.2

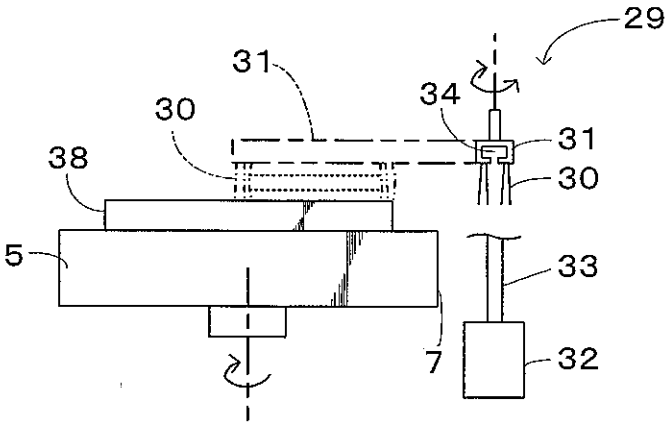


Fig.3

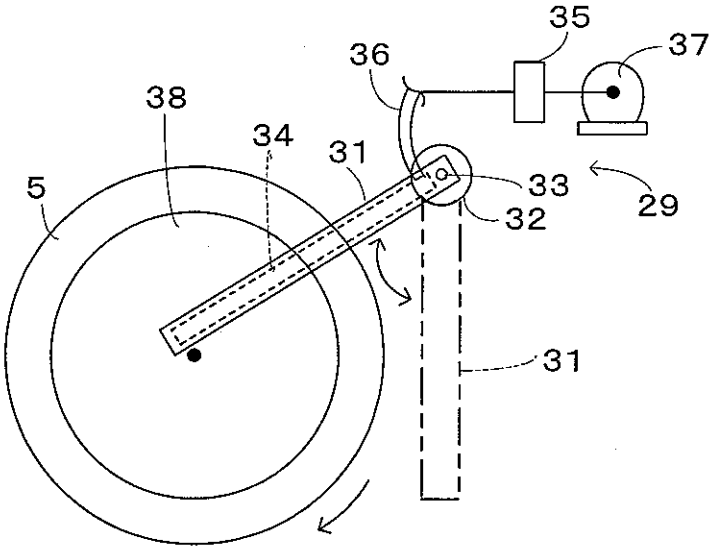


Fig.4

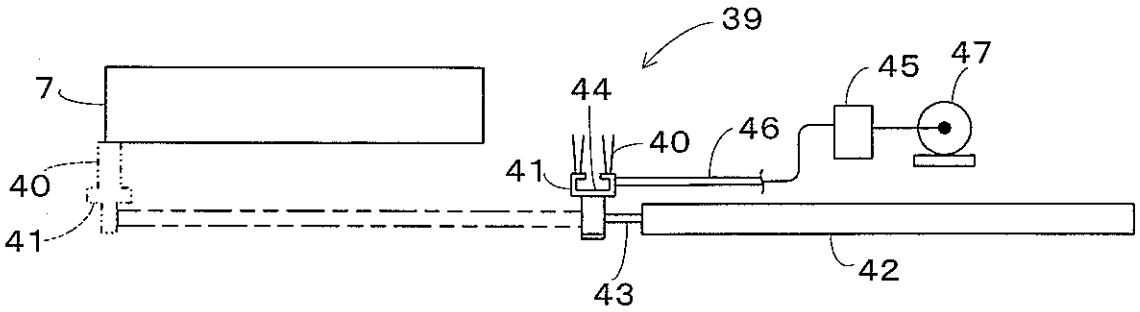


Fig.5

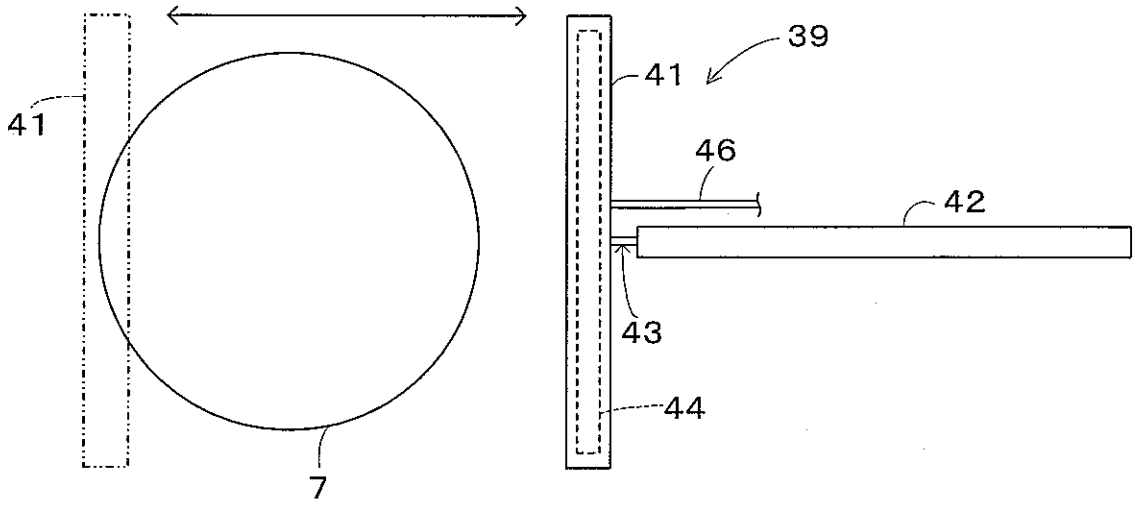


Fig.6

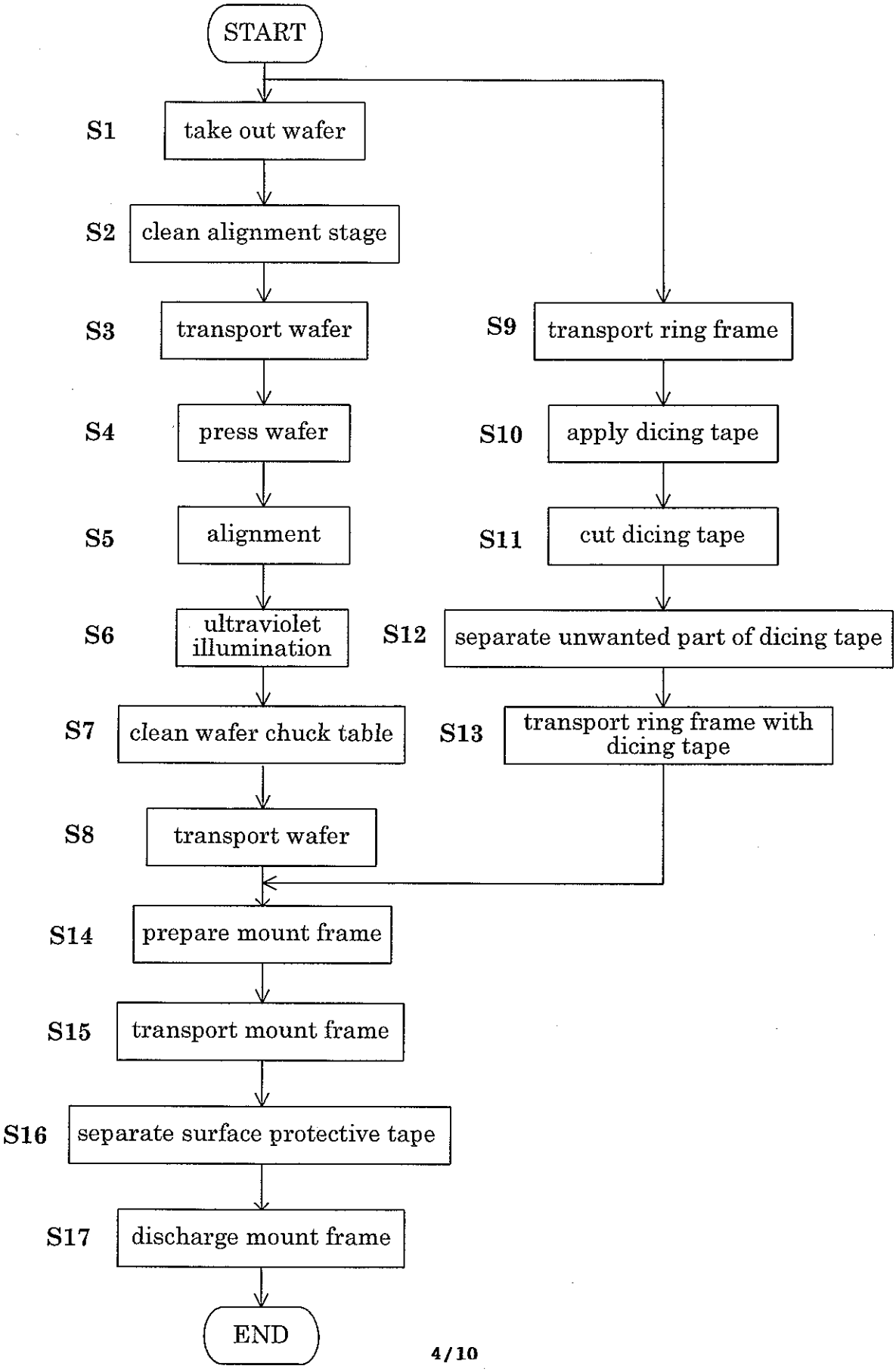

START
S1
take out wafer
S2
clean alignment stage
S3
transport wafer
S4
press wafer
S5
alignment
S6
ultraviolet illumination
S7
clean wafer chuck table
S8
transport wafer
S9
transport ring frame
S10
apply dicing tape
S11
cut dicing tape
S12
separate unwanted part of dicing tape
S13
transport ring frame with dicing tape
S14
prepare mount frame
S15
transport mount frame
S16
separate surface protective tape
S17
discharge mount frame
END

Fig.7

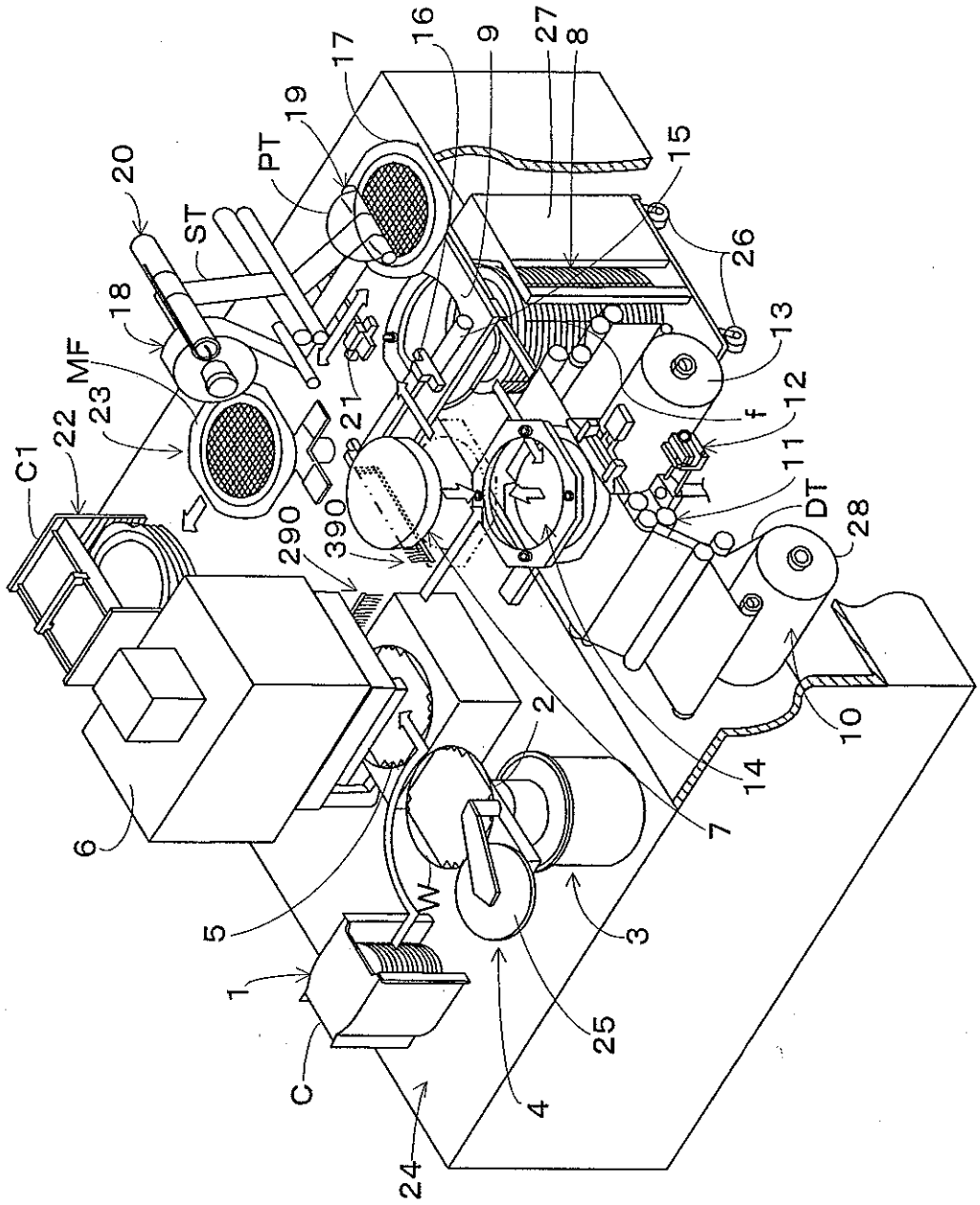

C1
22
MF
23
18
20
ST
PT
19
17
16
9
27
8
15
26
13
12
11
DT
28
10
14
7
2
3
25
4
24
C
1
5
W
6
290
390
21

Fig.8

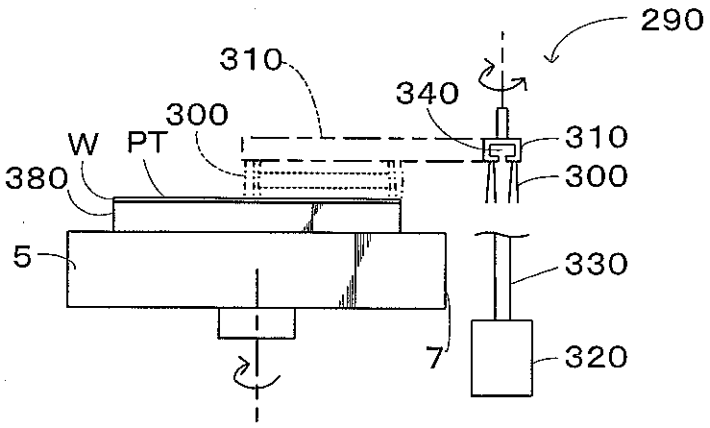

290
310
340
300
W
PT
310
380
300
5
330
7
320

Fig.9

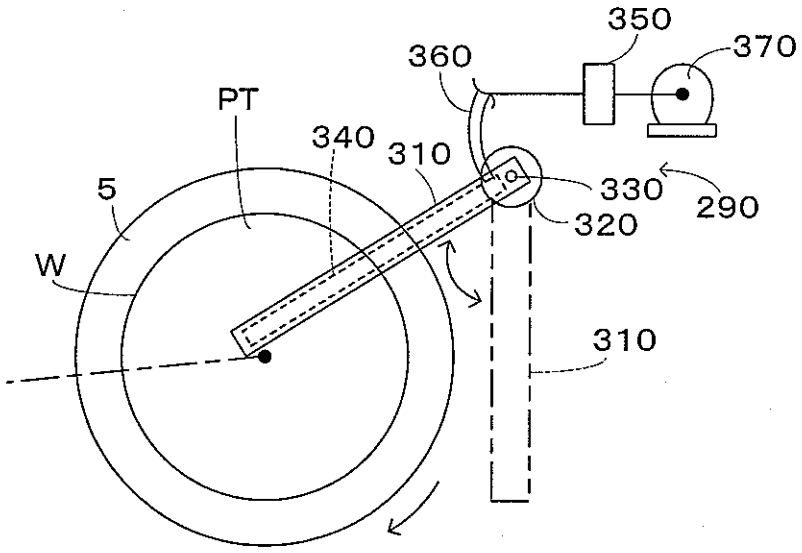

350
370
360
PT
340
310
5
330
290
320
W
310

Fig.10

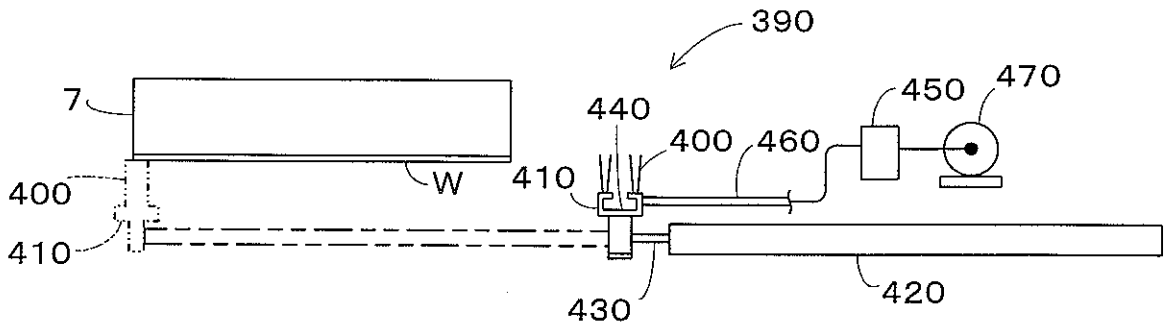

390
7
440
450
470
400
460
W
410
400
410
430
420

Fig.11

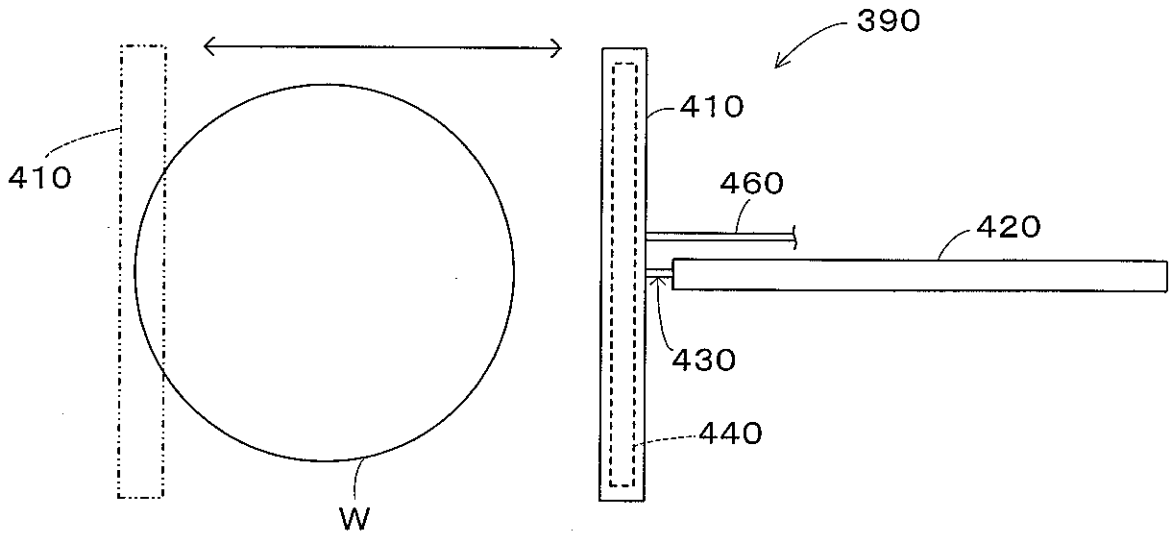

390
410
410
460
420
430
440
W

Fig.12

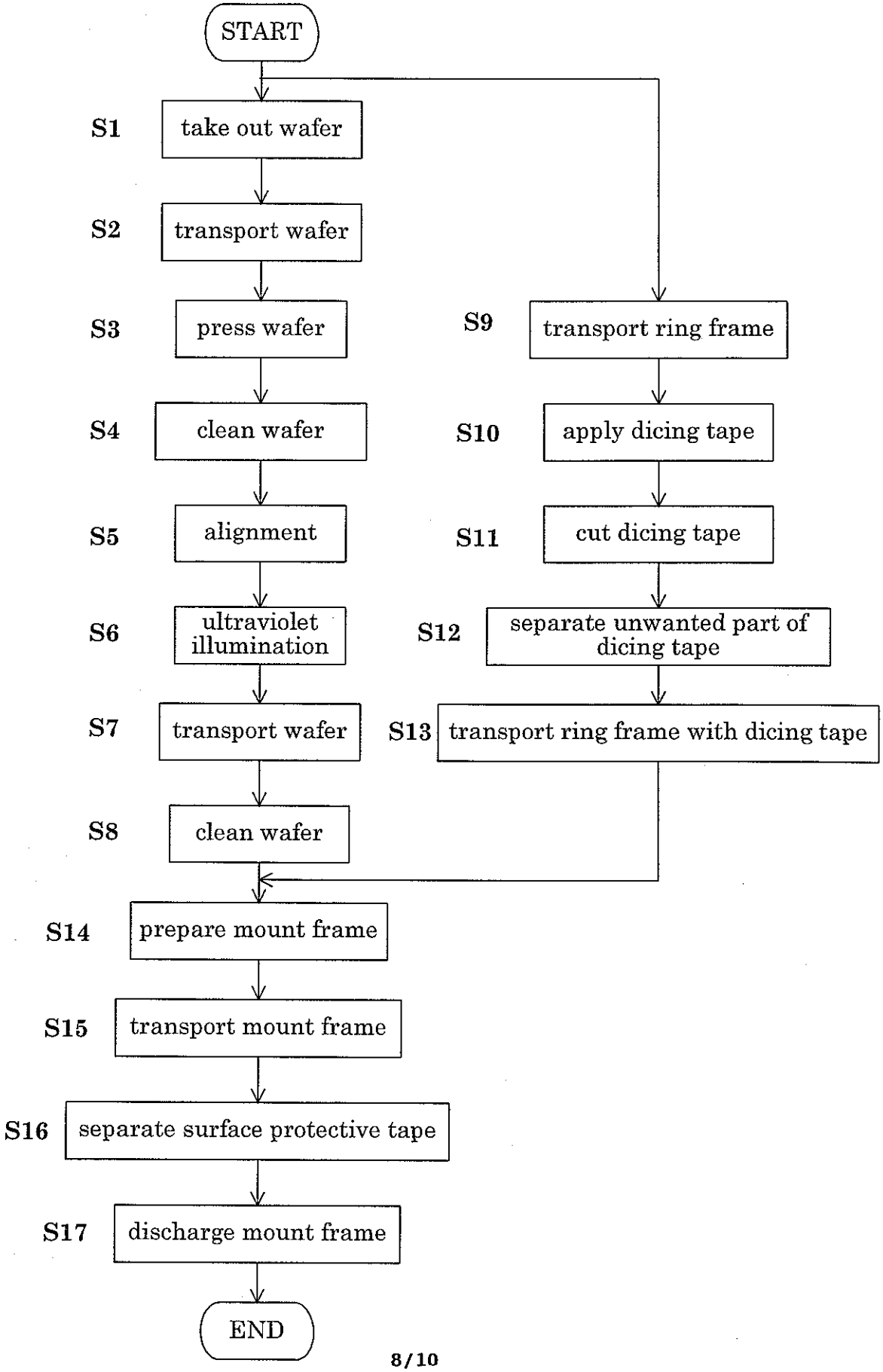

START
S1
take out wafer
S2
transport wafer
S3
press wafer
S4
clean wafer
S5
alignment
S6
ultraviolet illumination
S7
transport wafer
S8
clean wafer
S9
transport ring frame
S10
apply dicing tape
S11
cut dicing tape
S12
separate unwanted part of dicing tape
S13
transport ring frame with dicing tape
S14
prepare mount frame
S15
transport mount frame
S16
separate surface protective tape
S17
discharge mount frame
END

Fig.13

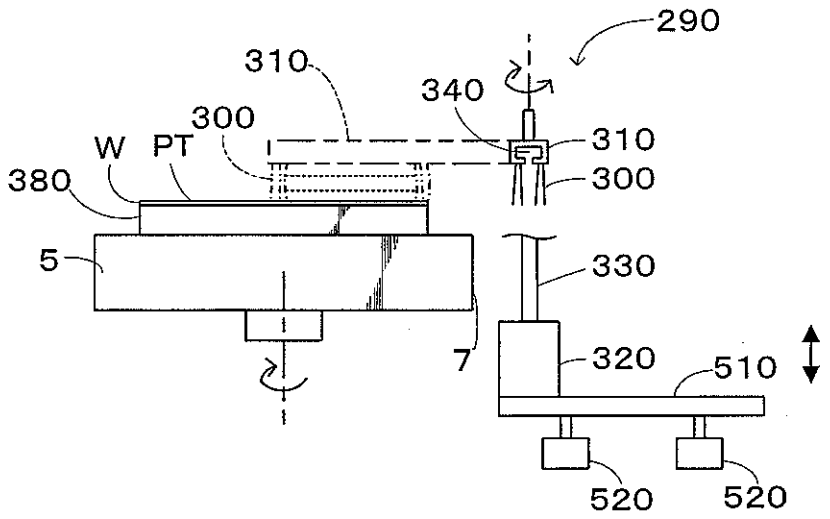

290
310
340
300
310
W
PT
300
380
5
330
7
320
510
520
520

Fig.14

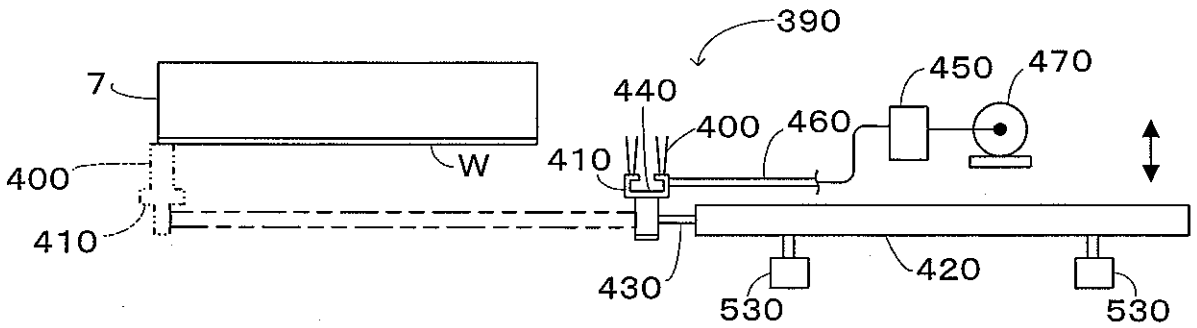
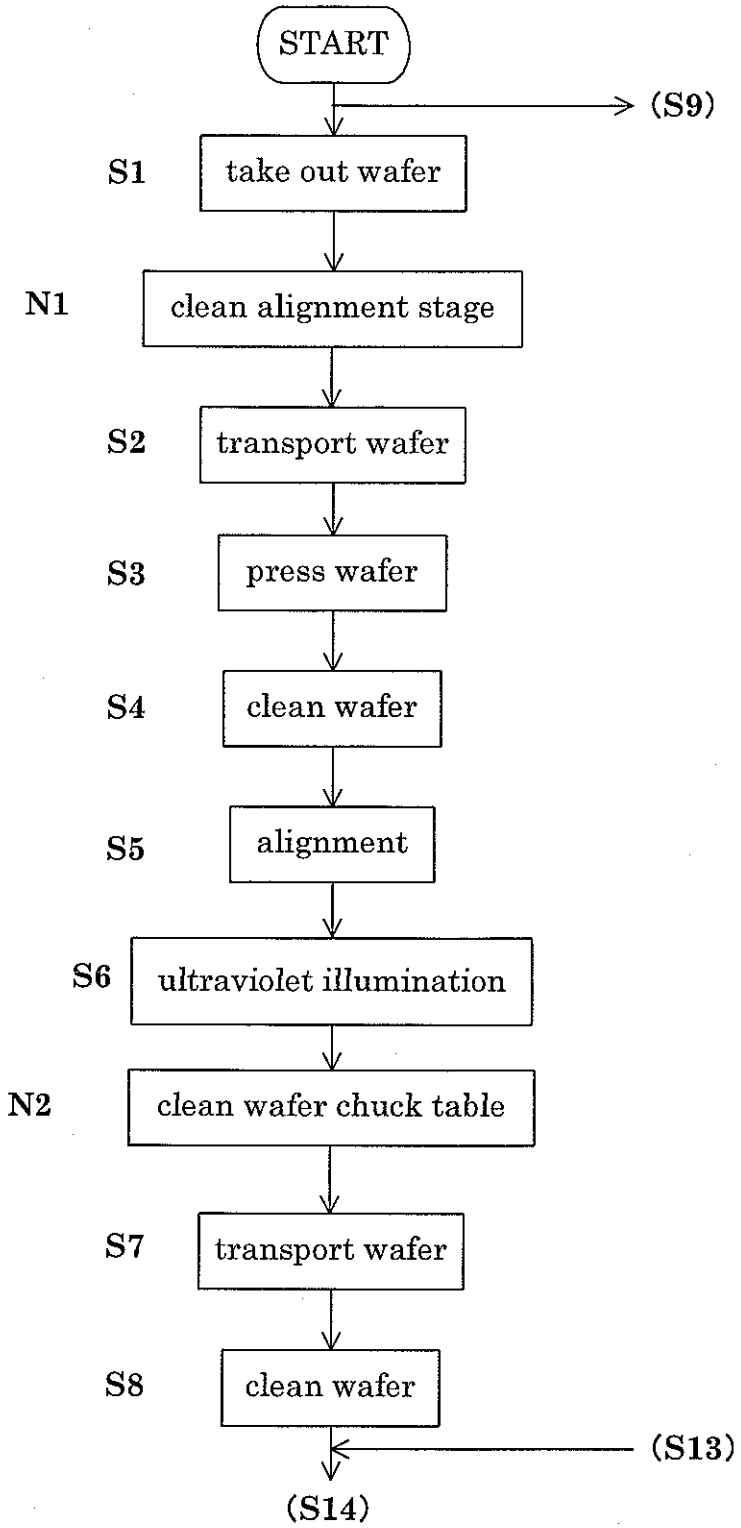

390
7
440
450
470
400
460
410
W
400
410
430
420
530
530

Fig.15


START
(S9)
S1
take out wafer
N1
clean alignment stage
S2
transport wafer
S3
press wafer
S4
clean wafer
S5
alignment
S6
ultraviolet illumination
N2
clean wafer chuck table
S7
transport wafer
S8
clean wafer
(S13)
(S14)